



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re application of: O'DONNELL

Attorney Docket No.:
LAM1P133/P0582

Application No.: 09/472,757

Examiner: UMEZ ERONINI, Dorette T.

Filed: December 27, 1999

Group: 1765

Title: INSITU POST ETCH PROCESS TO
REMOVE REMAINING PHOTORESIST AND
RESIDUAL SIDEWALL PASSIVATION

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CERTIFICATE OF MAILING

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Signed: Sue Funchess

Sue Funchess

AMENDMENT D

Box AF
Commissioner for Patents
Washington, D.C. 20231

E/A
L. J. M-E
4/23/2003

Dear Madame:

This is in response to the Final Office Action mailed January 2, 2003. Please consider the following remarks and amend the above-identified patent application as follows:

In the Claims:

Please cancel claim 20 and amend claims 1, 15, 17, and 19, as follows:

1. (Once Amended) A method for etching at least partially through a metal-containing layer disposed above a substrate, wherein part of said metal-containing layer is disposed below an etch mask and part of said metal-containing layer is not disposed below the etch mask, comprising the steps of:

placing the substrate in an etch chamber;

flowing an etchant gas into the etch chamber;